

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5007	(substrate near2 ((dielectric insulat\$3) near (layer film)) near2 ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 15:42
L2	361	1 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:12
L3	294	2 and (via\$1 open\$3 hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:12
L4	26	3 and (extend\$3 near through)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 16:14
L5	278	3 and through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:13
L6	5	("4935665" "5813753" "5985696" "6517218" "6531328").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/05/06 16:41
L7	11760	illuminat\$3 near (assembly apparatus)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:16
L8	4	7 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:11
L9	4923	7 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17

L10	3730	9 and (via\$1 open\$3 hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17
L11	3558	10 and through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17
L12	14	11 and (heat near spread\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:14
L13	4	7 and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:15
L14	463393	illuminat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:16
L15	127516	14 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17
L16	88179	15 and (via\$1 open\$3 hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17
L17	82387	16 and through	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:17
L18	2900	17 and ((thermal heat) near (dissipat\$4 spread\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:19

L19	256	11 and ((thermal heat) near (dissipat\$4 spread\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:19
S1	54	("20010001207" "20010010449" "20020024055" "20020113244" "20020176251" "20030001488" "20030052594" "20030057421" "20030142500" "20030178627" "20040164325" "20040166249" "5140248" "5227008" "5299222" "5420768" "5574817" "5611017" "5634711" "5808794" "5882774" "5967653" "6224216" "6560038" "6603258" "6692250").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 10:38
S2	10882	257/13,79-103,918.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 10:40
S3	762	S2 and (LED with (via\$1 open\$3 hole\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:13
S4	10	S3 and (flexible near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:15
S5	224	S3 and illuminat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:10
S6	10	S4 and (flexible substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 10:51
S7	28	S5 and (((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:31

S8	192	S5 and (flexible substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:15
S9	109	S8 and ((dielectric insulat\$3) with (metal conduct\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:03
S10	833365	"257"/\$.ccls. "438"/\$.ccls. "313"/\$.ccls. "428"/\$.ccls. "315"/\$.ccls. "349"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:05
S11	67063	S10 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 15:43
S12	12735	S11 and illuminat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:06
S13	7597	S12 and (flexible substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:07
S14	0	S13 and (((conduct\$3 metal) near (layer film)) with (heat near spread\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:15
S15	869	S13 and (((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:08
S16	47	S13 and (heat near spread\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:13

S17	117699	(LED (light near emit\$4)) with (via\$1 open\$3 hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:30
S18	943	S17 and (flexible near substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:15
S19	34885	S17 and (flexible substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:15
S20	33	S19 and (((conduct\$3 metal) near (layer film)) with ((thermal heat) near (dissipat\$4 spread\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:19
S21	39	S17 and (((conduct\$3 metal) near (layer film)) with ((thermal heat) near (dissipat\$4 spread\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:21
S22	1642	(((conduct\$3 metal) near (layer film)) with ((thermal heat) near (dissipat\$4 spread\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 17:18
S23	182	S22 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:39
S24	23089	(LED (light near emit\$4)) near2 (via\$1 open\$3 hole\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:36
S25	791	S24 and (((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:32

S26	191	S24 and (substrate with ((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:38
S27	21	(LED (light near emit\$4)) near2 (via\$1 open\$3 hole\$1) near2 (extend\$3 near through)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:39
S28	39904	(substrate with ((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 15:42
S29	3088	S28 and (LED (light adj emit\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 11:39
S30	87	S29 and (via\$1 open\$3 hole\$1) near2 (extend\$3 near through)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/05/06 15:44